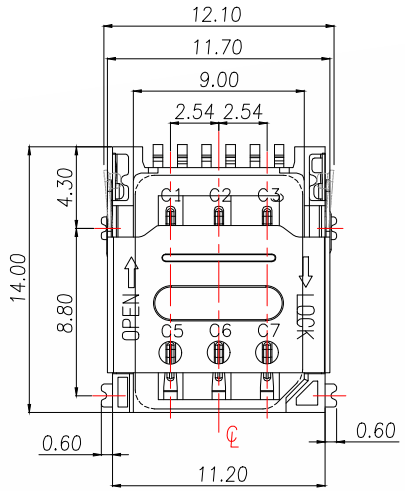
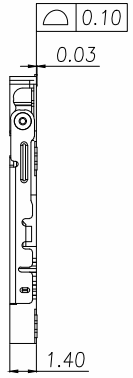
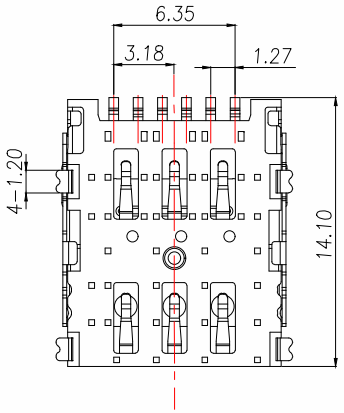
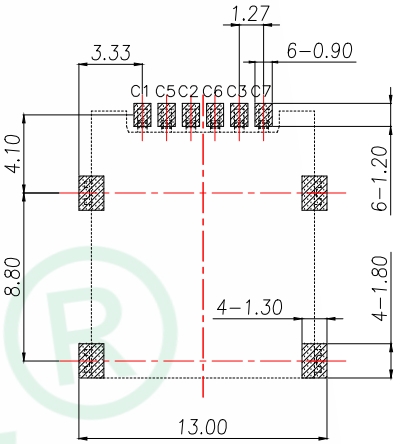
REV.	DESCRIPTION	ECN NO.	NAME	DATE







NANO SIM CARD	
Pin No.	NAME
C1	VCC OF SIM
C2	RST OF SIM
C3	CLK OF SIM
C5	GND OF SIM
C6	VPP OF SIM
C7	I/O OF SIM
C4/C8	N/A

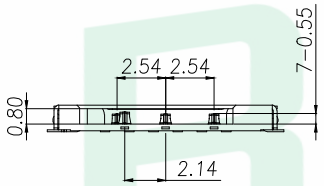


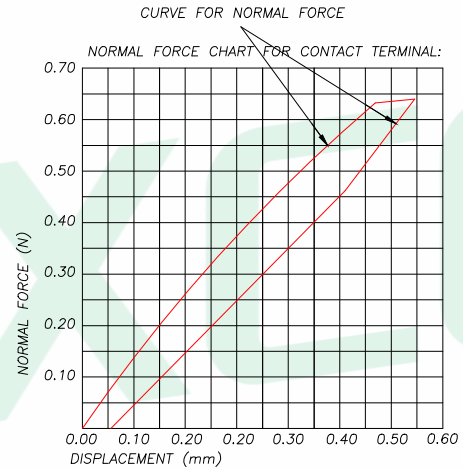
PAD AREA

KEEP OUT AREA

RECOMMENDED PCB LAYOUT

GENERAL TOLERANCE ±0.05

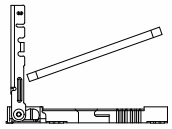




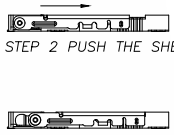
NOTES:
1.MATERIAL:
- 1.1 Housing:High Temperature Thermoplastic UL94V-0; Color Black.
- 1.2 Terminal:Copper Alloy,T=0.12mm.
- 1.3 Shell:Stainless Steel,T=0.20mm.

2.FINISH:
- 2.1 Terminal:Plated Gold on The Contact Area and Solder Tails
- 2.2 Peg:Plated Gold on the bottom of the Solder Tails, Tin Plated over all.

3.SPECIALITY:
- 3.1 Rated current:0.5A
- 3.2 Rated voltage:50V
- 3.3 Contact Resistance:80mΩMAX
- 3.4 Insulation Resistance:100MΩMIN 100V DC
- 3.5 Dielectric withstanding voltage: 100V AC.
- 3.6 Solder ability:245±5°C,5±0.5s.
- 3.7 Operating condition:Temperature: -40°C~+85°C Humidity: 80% R.H MAX

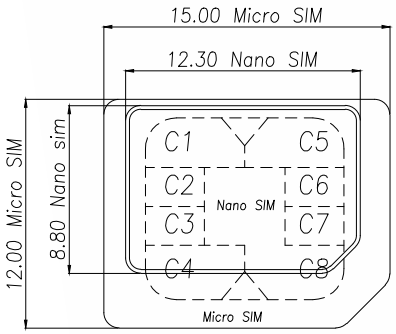


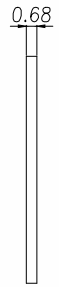
STEP 1 INSERT NANO SIM CARD



STEP 2 PUSH THE SHELL

STEP 3 FINISH





NO.	PART NAME	Q'TY	DESCRIPTION	NOTE
3	TERMINAL	6	C5210-EH,T=0.12	G/F PLATING
2	BASE INSULATOR	1	LCP+GF30%	BLACK
1	SHELL	1	SUS304-H,T=0.15	AU/Ni PLATING

GENERAL TOLERANCE

DIM.	TOL.
x.	±0.50
x.x	±0.20
x.xx	±0.10
GENERAL ANGLE:	
x.°	±2°
x.x°	±1°

DONGGUAN BAOXUN PRECISION TECHNOLOGY CO., LTD

BXCONN®

TITLE: NANO SIM CARD CONN. 6PIN 1.4H

DWG. NO.: SIM301-GZ6P

CHECKED: MAX

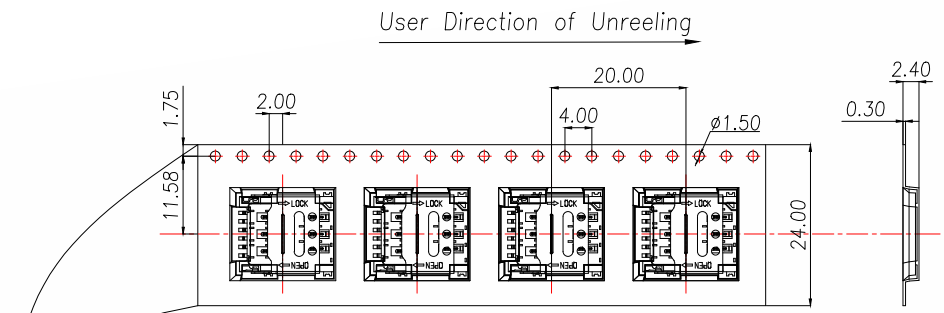
PART NO.: SIM301-GZ6P

DRAWN: ELLA

UNIT:	SCALE:	SHEET:	DWG. SIZE:	LAYER:	APPROVED: WILL
mm	none	1of 2	A4	bxconn	

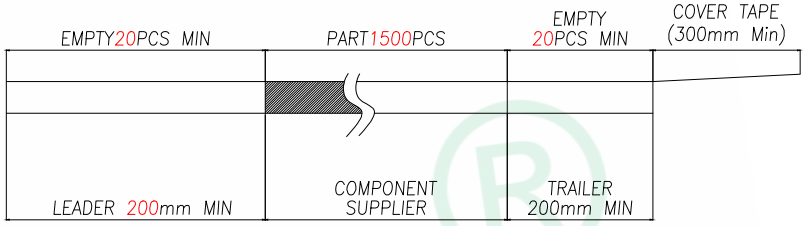
WWW.BXCONN.COM 东莞市宝讯精密技术有限公司 ARTICLE: BX-CN-001-A

REV.	DESCRIPTION	ECN NO.	NAME	DATE

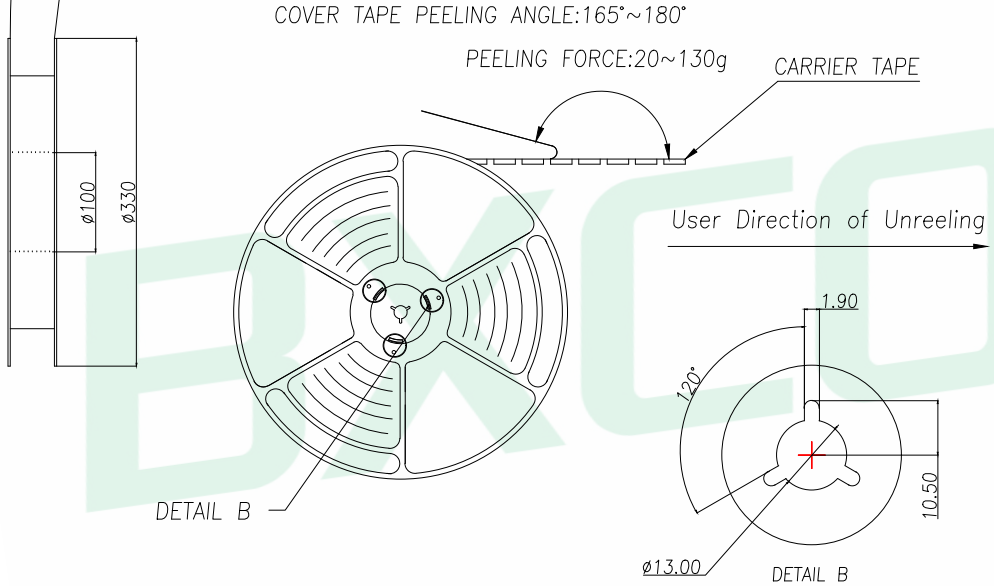


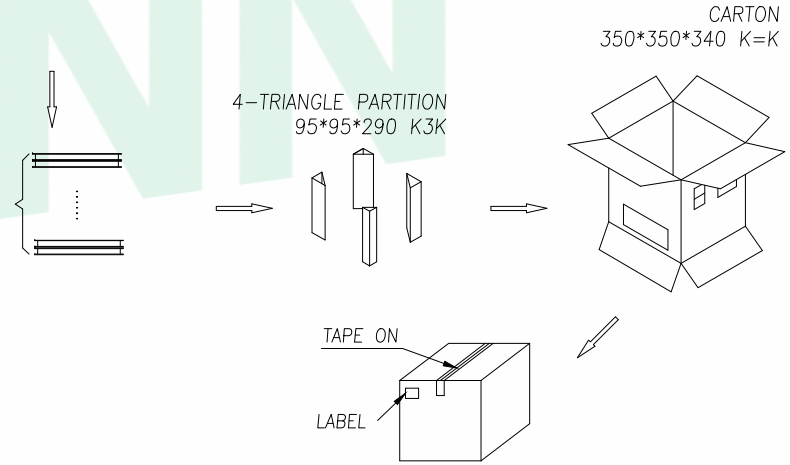
NOTES

1. NUMBER OF CONNECTORS:1500PCS/REEL
2. LEAD TAPE LENGTH



3.QUANTITY:15000PCS/CARTON





GENERAL TOLERANCE DIM. TOL. x. ±0.50 x.x ±0.20 x.xx ±0.10 GENERAL ANGLE: x.° ±2° x.x° ±1°	DONGGUAN BAOXUN PRECISION TECHNOLOGY CO., LTD					BXCONN®
	TITLE: NANO SIM CARD CONN. 6PIN 1.4H					
	DWG. NO.: SIM301-GZ6P				CHECKED: MAX	
	PART NO.: SIM301-GZ6P				DRAWN: ELLA	
	UNIT: mm	SCALE: none	SHEET: 2 of 2	DWG. SIZE: A4	LAYER: bxconn	APPROVED: WILL